TO

		OF REVIS	NONS	BY	CHKD	DATE	\bot	COUNT	DESCRIPTION OF	- KEVISIONS	BY	CHKD	DAT	ΓE
								400-1-000						
							\triangle							
APPLICABLE	STANE	ARD												
1	RATING PERATURE	= PANGE	-35 °	СТ	0	85 °C(NC	TE 1		RAGE PERATURE RANGE	-10°C	Т	0 6	60 °C	;
RATING VO		250 V AC APP					APPL	LICABLE DE1E XXXX			PCF			
	······································				loor				TO ATTACO DE BAROLTO					
CU	RRENT	1 AVVG30 \sim 20 : 0.5 \sim 3A RANG							UL1007,	1061	:AWC	330~	-20	
					S	PECIF	ICA'	TIOI	NS					
ITEM			•	TES	T ME	THOD			REQU	JIREMEN	TS		QT	AT
CONSTRUCT	TION				~									
GENERAL EXAMI	NATION	VISUALL	Y AND	BY M	EASUF	RING INSTR	UMEN	IT.	ACCORDING TO D	DRAWING.			×	×
MARKING		CONFIR	MED V	SUAL	LY.								×	×
ELECTRIC C	HARA								8					
CONTACT RESIST	TANCE	mA	(DC OF	₹ 1000) Hz).				mΩ MAX.					
CONTACT RESISTANCE		20 mV MAX. 1 mA(DC OR 1000 Hz).							30 mΩMAX.				×	
MILLIVOLT LEVEL METHOD:	-													
NSULATION		500V DC			***************************************				1000 MΩ MIN.			,	+	†
RESISTANCE		650 V AC FOR 1 min.							No El Agua ou En	00.005440	O14/N			<u> </u>
VOLTAGE PROOF									NO FLASH OVER	OK BREAKD	OWN.		<u> ×</u>	
MECHANICA		RACT				16E			INGESTION FOR	\\\\\\\\\\	1443/			т
CONTACT INSERTAND EXTRACTION			BY	SIE	L GAL	JGE.		,	INSERTION FORCE		MAX.			A
FORCES														
INSERTION AND WITHDRAWAL FORCES									INSERTION FORCE		MAX. N MIN.			
MECHANICAL.		30 TIME!	SINSE	RTION	IS AND	EXTRACT	ONS.		① CONTACT RES				$+_{\times}$	
OPERATION									D NO DAMAGE,	CRACK AND	LOOSE	ENESS,		
VIBRATION		EBEOLIE	NCV 1	0.70.6	55 Hz	SINGLE AM	DI ITI I	DE	OF PARTS. I NO ELECTRICA	U DISCONTIN	LIITYO	E1c	 	ļ
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75mm, m/s ² AT 2 h, FOR 3 DIRECTIONS.							② CONTACT RES				×	AT official days
SHOCK		490 m/s ² DIRECTIONS OF PULSE 11 ms AT							3 NO DAMAGE,	CRACK AND	LOOS	ENESS,	X	
		3 TIN	AE FOR	3	DIREC	CTION.			OF PARTS.					
ENVIRONME	NTAL	CHAR	ACTE	RIS	TICS	<u> </u>		eum mitama k musabu cm	der spierre eigen met der der eine verscheit felle eine versche er der der eine der eine der eine der eine der					
RAPID CHANGE	5F	TEMPER	RATURI			35→85 →			① CONTACT RES				×	
TEMPERATURE		TIME 30→ 5 MAX→ 30 → 5 MAX min UNDER 5 CYCLES.							② INSULATION RESISTANCE:1000MΩ MIN. ③ NO DAMAGE, CRACK AND LOOSENESS.				1	
		IIINDED.							OF PARTS.					
		UNDER							OF PARTS.					
DAMP HEAT					c, 90 1	ro 95 %, 96	h.		CONTACT RES				×	
DAMP HEAT (STEADY STATE)					c, 90 1	ΓΟ 95 %, 96	h.		① CONTACT RES ② INSULATION R	RESISTANCE:	500 M	ΩΜΙΝ.	×	(Processes)
DAMP HEAT					C, 90 1	ГО 95 %, 96	h.		CONTACT RES	RESISTANCE:	500 M	ΩΜΙΝ.	×	12072/9000000
DAMP HEAT (STEADY STATE)			D AT 4	0±2°		0 95 %, 96 TER SPRA			CONTACT RES INSULATION R NO DAMAGE, I OF PARTS. CONTACT RES	RESISTANCE: CRACK AND SISTANCE:	500 M	IΩMIN. ENESS,	×	
DAMP HEAT (STEADY STATE) CORROSION SAL	T MIST	EXPOSE	ED AT 4	0±2°	LT WA	ATER SPRA			CONTACT RES INSULATION R NO DAMAGE, OF PARTS. CONTACT RES NO HAEAVY C	RESISTANCE: CRACK AND SISTANCE: CORROSION.	500 M LOOSI mΩ M	IΩMIN. ENESS, IAX.	×	
DAMP HEAT (STEADY STATE) CORROSION SAL	T MIST	EXPOSE	ED AT 4	0±2°	NLT WA	ATER SPRA			CONTACT RES INSULATION R NO DAMAGE, I OF PARTS. CONTACT RES	RESISTANCE: CRACK AND SISTANCE: CORROSION. SISTANCE:	500 M LOOSI	IΩMIN. ENESS, IAX.	×	
DAMP HEAT	T MIST	EXPOSE EXPOSE	D IN D IN TANDA	0±2° % SA - PP RD: J	NLT WA	ATER SPRA R – h. 88)			ONTACT RES INSULATION R NO DAMAGE, OF PARTS. CONTACT RES NO HAEAVY C CONTACT RES	RESISTANCE: CRACK AND SISTANCE: CORROSION. SISTANCE: CORROSION.	500 M LOOSI mΩ M	IΩMIN. ENESS, IAX.	×	
DAMP HEAT (STEADY STATE) CORROSION SAL HYDROGEN SULI	T MIST	EXPOSE EXPOSE (TEST S' EXPOSE (TEST S'	ED IN - TANDA TANDA	0 ± 2 ° % SA - PP RD: Ji - PP	M FOR EIDA-3 M FOR EIDA-3	ATER SPRA R h. 88) R h. 89)	Y FOR		① CONTACT RES ② INSULATION R ③ NO DAMAGE, OF PARTS. ① CONTACT RES ② NO HAEAVY C ② NO HAEAVY C ① CONTACT RES ② NO HAEAVY C	RESISTANCE: CRACK AND SISTANCE: ORROSION. SISTANCE: ORROSION. SISTANCE: ORROSION.	500 MLOOSImΩ MmΩ NmΩ N	IΩMIN. ENESS, IAX.	×	
DAMP HEAT (STEADY STATE) CORROSION SAL HYDROGEN SULI SULPHUR DIOXIE	T MIST PHIDE DE	EXPOSE EXPOSE (TEST S' EXPOSE (TEST S' SOLDER	ED IN ED IN TANDA TANDA TANDA TANDA	% SA - PP RD: J - PP RD: J ERAT	M FOR EIDA-3 URE,	ATER SPRA R - h. 88) R - h. 89)			I CONTACT RES INSULATION R NO DAMAGE, OF PARTS. CONTACT RES NO HAEAVY C OCONTACT RES NO HAEAVY C OCONTACT RES NO HAEAVY C NO DEFORMATIC	RESISTANCE: CRACK AND SISTANCE: ORROSION. SISTANCE: ORROSION. SISTANCE: ORROSION. DN ON CASE	 500 M LOOSI mΩ M mΩ M OR 	IΩMIN. ENESS, IAX.	×	
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